micro resist **Product Information** Negative Tone Photoresist ma-N 400

The ma-N 400 series is an innovation in negative tone photoresists for flexible use for proximity and contact exposure. Full application compatibility with processing of conventional positive tone photoresists is guaranteed.

Thickness Range



The resist can be processed by spin- or roller-coating, spraying or dipping. Film thicknesses from 0.5 to 9 µm can be obtained in one step depending on the concentration of the resist solution and the spinning speed.

Spectral Sensitivity



UV-VIS Absorbance of ma-N 400

Processing

The processing of the ma-N 400 series is fully compatible to the processing of positive tone photoresists.

Variable edge shapes (qualified for lift-off) can be achieved by varying the processing conditions.

technology

Deposition Stability

ma-N 400 exhibits high resistance to acidic and alkaline etching solutions and plating bathes (pH 1 to 13). Therefore the resist is well suited for metallization processes.

Stripping

The chemical composition of ma-N 400 allows easy and residue-free resist removal after exposure.



SEM micrograph of a wheel-type resist pattern in ma-N 490

Pattern Transfer

Depending on the film thickness a resolution to 0.4 µm is possible. ma-N 400 exhibits a good adhesion on conventional substrate materials.

Environmental and Health Protection

All harmful organic solvents in resist and developer were substituted and are based on safe solvents.

